

D

C

B

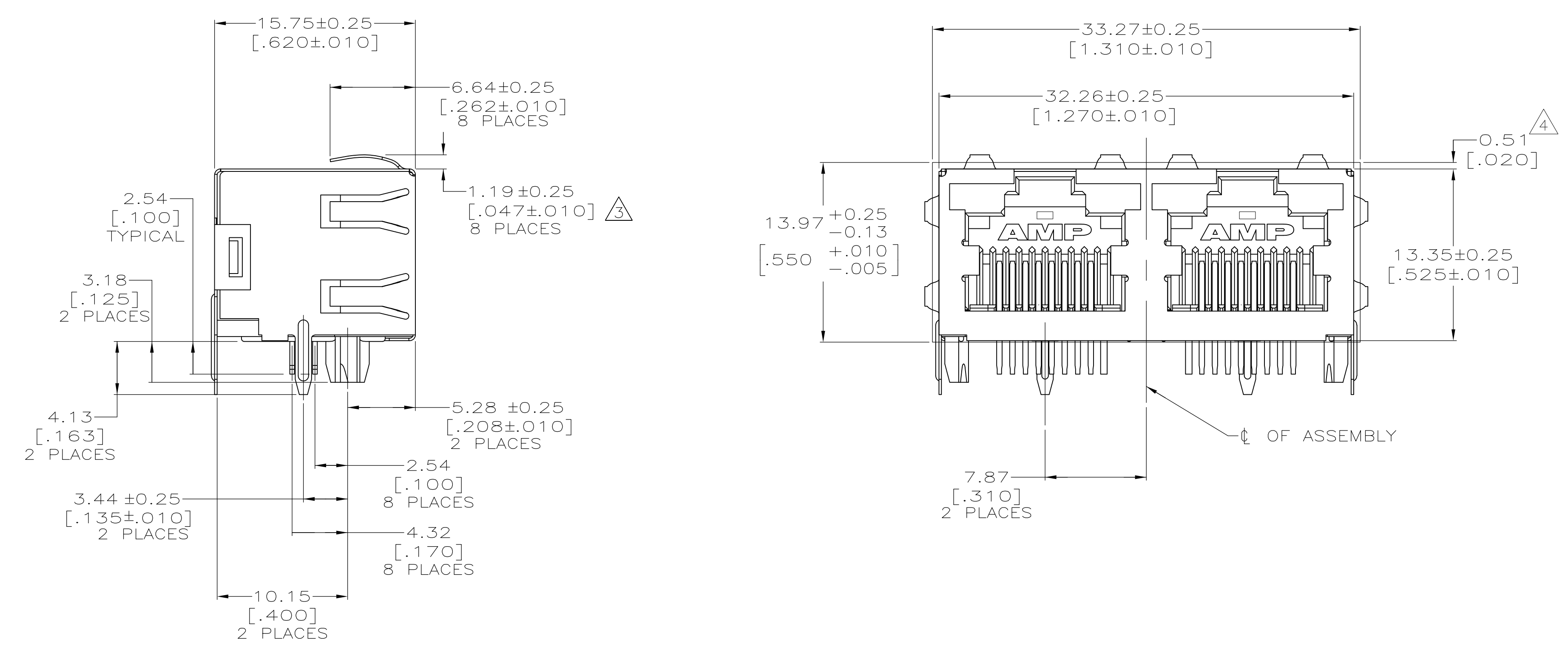
A

D

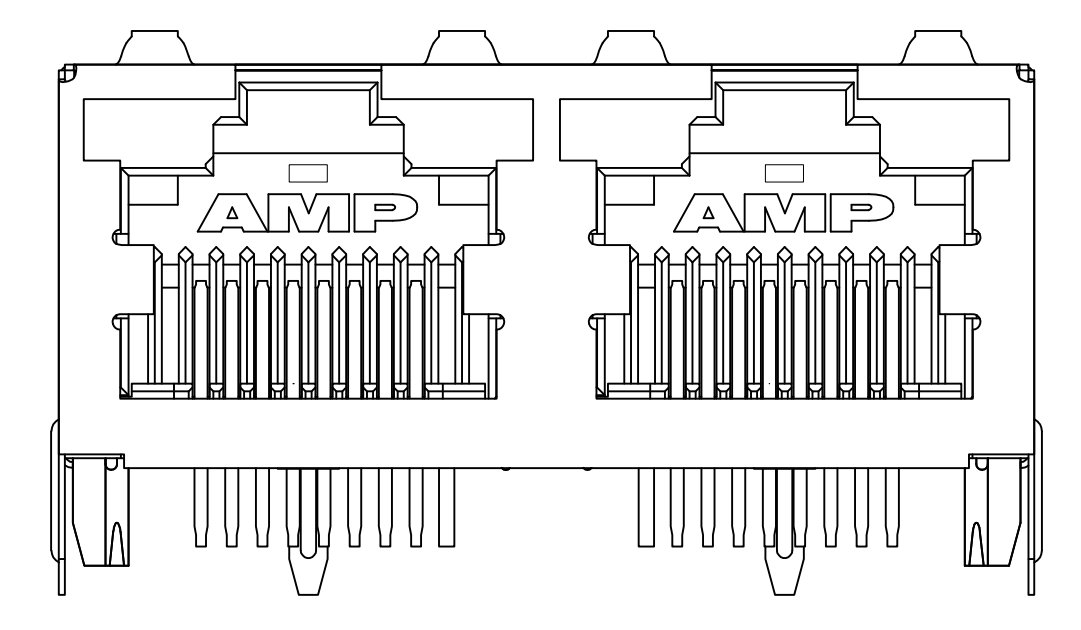
C

B

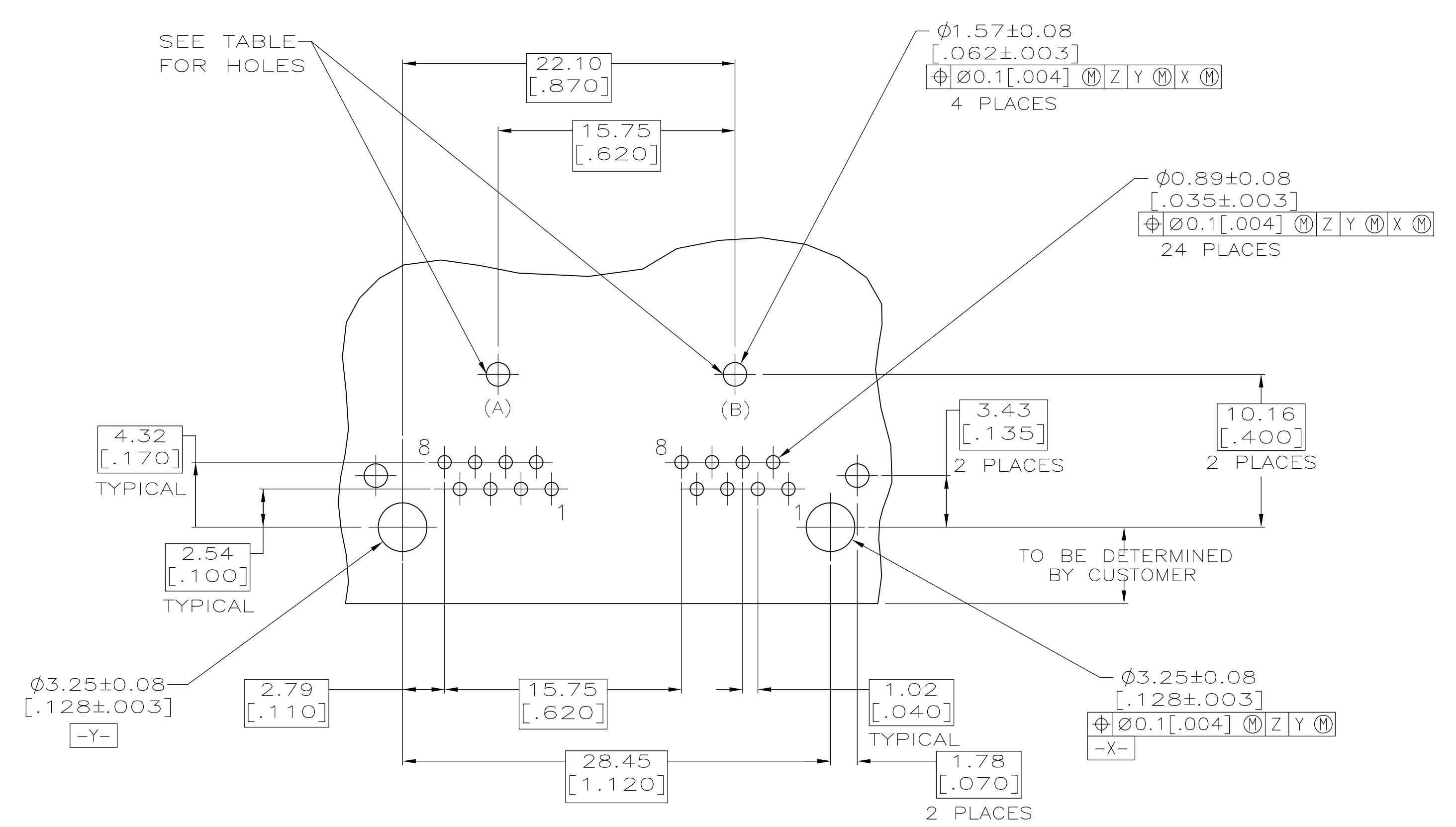
A



- ⚠ MATERIAL: HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μ m[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μ m[.000050] MINIMUM THICK NICKEL.
SHIELD – 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μ m[.000050] MINIMUM SATIN NICKEL WITH 2.03 μ m[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
- ⚠ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- ⚠ TAPE&REEL PACKAGING WITH ANTISTATIC.



PN: 6116522-3
SIMILAR TO 6116522-1, BUT WITHOUT EMI FINGERS ON BOTH SID



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

2	4	TRAY	6116522-3
2	8	⚠ T&R	6116522-2
2	8	TRAY	6116522-1
REAR TABS	EMI FINGERS	PACKAGE	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:
mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PL	±	-
1 PL	±	-
2 PL	±	0.25[.01]
3 PL	±	0.13[.005]
4 PL	±	-
ANGLES	±	-

MATERIAL

⚠

DWN
L. VARELA - DOCKS
CHK
J. WESTMAN
APVD
S. FLICKINGER

10JUN2005
10JUN2005

TE Connectivity

NAME
INVERTED MODULAR JACK ASSEMBLY,
1X2, SHIELDED, PANEL GROUND

PRODUCT SPEC
108-1163-4

APPLICATION SPEC
114-2154

SIZE
A1

CAGE CODE
00779

DRAWING NO
6116522

RESTRICTED TO
-

CUSTOMER DRAWING

SCALE
4:1

SHEET
1 OF 1

REV
A4